

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	20135053	(@ad<"20010110") 438/106.ccls. and (wafer with caps)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/02 13:37
L2	20135052	(@ad<"20010110") 438/106.ccls. and (wafer adj cap\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/02 12:55
L3	576197	L2 and (mold or molding)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/02 12:54
L4	3	(@ad<"20010110") and 438/106.ccls. and (wafer adj cap\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/02 13:31
L5	19	(@ad<"20010110") and "438"/\$.ccls. and (wafer adj cap\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/02 12:58
L6	229	(@ad<"20010110") and (press or push or molding or mold) and ((chip or die or wafer) adj (cap\$1 or lid))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/02 13:32
L7	158	L6 and mold\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/02 12:59
L8	1076	(@ad<"20010110") and ((press or push) with (cap\$1 or lid or sink\$ or spreader\$1)) and (chip or ide or wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/02 13:29

L9	2500	(@ad<"20010110") and ((press or push) with (cap\$1 or lid or sink\$ or spreader\$1)) and (chip or die or wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/02 13:05
L10	709	L9 and (mold or molding)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/02 13:30
L11	3	(@ad<"20010110") and ((resin or plastic) with (wafer with caps))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/02 13:29
L12	4563	(@ad<"20010110") and ((resin or thermoplastic or epoxy or plastic) with (cap\$1 or lid or sink\$ or spreader\$1)) and (chip or ide or wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/02 13:30
L13	638	(@ad<"20010110") and ((resin or thermoplastic or epoxy or plastic) near (cap\$1 or lid or sink\$ or spreader\$1)) and (chip or ide or wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/02 13:30
L14	1344	(@ad<"20010110") and ((resin or thermoplastic or epoxy or plastic) near (cap\$1 or lid or sink\$ or spreader\$1)) and (chip or die or wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/02 13:30
L15	622	L14 and (mold or molding)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/02 13:30
L16	544	L15 not L10	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/02 13:30

L17	1	(@ad<"20010110") and 257/704, 710.ccls. and (wafer adj cap\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/02 13:32
L18	26	(@ad<"20010110") and "257"/\$. ccls. and (wafer adj cap\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/02 13:32
L19	4	L18 and (press or push or molding or mold)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/02 13:36
L20	13208	((cavity with plate) or push or molding or mold) with (caps or lids or array))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/02 13:37
L21	13379	L20 (@ad<"20010110") and (wafer with caps)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/02 13:37
L22	4	L20 and (@ad<"20010110") and (wafer with caps)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/02 13:39
L23	1	("6483030").PN.	USPAT; USOCR	OR	OFF	2005/09/02 14:32
L24	120	(@ad<"20010110") and ((plate or mold) near (polyimide or polymer or tape or ceramic or aluminum)) and (encapsulant or encpasualte)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/02 14:34